

Amendments to the Claims

1. (Currently Amended) A heat-dissipation structure of a plasma display panel device including a plasma display panel and a drive circuit for driving the plasma display panel, comprising:

a plurality of circuit boards; and

electronic components making up the drive circuit and mounted separated on said plurality of circuit boards,

wherein said plurality of circuit boards are arranged approximately in parallel to each other.

2. (Original) The heat-dissipation structure of the plasma display panel according to claim 1, wherein an electronic component with the heat-generating property out of said electronic components making up the drive circuit is mounted on a required circuit board out of said plurality of circuit boards.

3. (Original) The heat-dissipation structure of the plasma display panel device according to claim 2, wherein said required circuit board is supported by a metal-made build-up frame thermally-conductively installed on a metal-made casing of the plasma display panel device and being in contact with at least part of said electronic components with the heat-generating property mounted on the required circuit board.

4. (Original) The heat-dissipation structure of the plasma display panel according to claim 3, wherein said electronic components with said heat-generating property are mounted separately on both faces of said required circuit board, and the electronic component mounted on one face of the required circuit board are in contact with said build-up frame.

5. (Original) The heat-dissipation structure of the plasma display panel according to claim 4, wherein said electronic component mounted on the one face of said required circuit board and being in contact with said build-up frame is a heat-generating module.

6. (Currently Amended) The heat-dissipation structure of the plasma display panel according to claim 2, wherein part of the electronic components with the heat-generating property out of said electronic components making up the drive circuit is mounted on said required circuit board out of said plurality of circuit boards, and ~~another~~ another electronic component with the heat-generating property is mounted on a circuit board out of said plurality of circuit boards other than said required circuit board while being in thermal-conductive contact with a metal-made casing of the plasma display panel device.

7. (Original) The heat-dissipation structure of the plasma display panel according to claim 7, wherein said another electronic component with the heat-

generating property is thermal-conductively installed to the metal-made casing of the plasma display panel device and is in contact with a metal-made build-up frame supporting said required circuit board.

8. (Original) The heat-dissipation structure of the plasma display panel according to claim 6, wherein said another electronic components with the heat-generating property are a heat-generating module.

9. (Original) A heat-dissipation structure of a plasma display panel including a plasma display panel and a drive circuit for driving the plasma display panel, comprising electronic components making up the drive circuit and mounted separately on both faces of a circuit board.

10. (Original) The heat-dissipation structure of the plasma display panel according to claim 9, wherein said circuit board having both the faces on which said electrode components are separately mounted is supported by a metal-made build-up frame, installed thermal conductively to a metal-made casing of the plasma display panel device and being in contact with part of at least the electronic components with the heat-generating property out of the electronic components mounted on the circuit board.

11. (Original) The heat-dissipation structure of the plasma display panel according to claim 10, wherein the electronic component mounted on said circuit board and being in contact with the build-up frame is a heat-generating module.